# **ON Semiconductor**

# Is Now



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# **ESD Protection Diode Array**

# Low Clamping Voltage

This quad monolithic silicon voltage suppressor is designed for applications requiring transient overvoltage protection capability. It is intended for use in voltage and ESD sensitive equipment such as computers, printers, business machines, communication systems, medical equipment, and other applications. Its quad junction common anode design protects four separate lines using only one package. These devices are ideal for situations where board space is at a premium.

#### **Features**

- Low Clamping Voltage
- Stand Off Voltage 3 V
- Low Leakage < 1 μA @ 3 V
- SC-88A Package Allows Four Separate Unidirectional Configurations
- IEC1000-4-2 Level 4 ESD Protection
- SZ Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- Pb-Free Package is Available\*

#### **Mechanical Characteristics:**

- Void Free, Transfer-Molded, Thermosetting Plastic Case
- Corrosion Resistant Finish, Easily Solderable
- Package Designed for Optimal Automated Board Assembly
- Small Package Size for High Density Applications



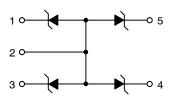
## ON Semiconductor®

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SCALE 2:

SC-88A/SOT-323 CASE 419A



#### **MARKING DIAGRAM**



61 = Device Code

M = Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MSQA6V1W5T2G	SC-88A (Pb-Free)	3,000 / Tape & Reel
SZMSQA6V1W5T2G	SC-88A (Pb-Free)	3,000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

<sup>\*</sup>T2 Suffix Devices are Packaged with Pin 1 Opposing Sprocket Hole.

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Peak Power Dissipation @ 20 μs @T <sub>A</sub> ≤ 25°C (Note 1)	P <sub>pk</sub>	150	W
Steady State Power – 1 Diode (Note 2)	P <sub>D</sub>	385	mW
Thermal Resistance Junction-to-Ambient Above 25°C, Derate	$R_{ hetaJA}$	325 3.1	°C/W mW/°C
Maximum Junction Temperature	T <sub>Jmax</sub>	150	°C
Operating Junction and Storage Temperature Range	T <sub>J</sub> T <sub>stg</sub>	-55 to +150	°C
ESD Discharge MIL STD 883C – Method 3015–6 IEC1000–4–2, Air Discharge IEC1000–4–2, Contact Discharge	V <sub>PP</sub>	16 16 9	kV
Lead Solder Temperature (10 s duration)	T <sub>L</sub>	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

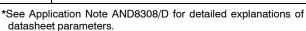
- Non-repetitive current per Figure 5. Derate per Figure 10.
   Only 1 diode under power. For all 4 diodes under power, P<sub>D</sub> will be 25%. Mounted on FR-4 board with min pad.

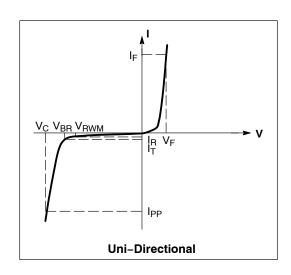
See Application Note AND8308/D for further description of survivability specs.

#### **ELECTRICAL CHARACTERISTICS**

(T<sub>A</sub> = 25°C unless otherwise noted)

Symbol	Parameter
I <sub>PP</sub>	Maximum Reverse Peak Pulse Current
V <sub>C</sub>	Clamping Voltage @ I <sub>PP</sub>
V <sub>RWM</sub>	Working Peak Reverse Voltage
I <sub>R</sub>	Maximum Reverse Leakage Current @ V <sub>RWM</sub>
$V_{BR}$	Breakdown Voltage @ I <sub>T</sub>
I <sub>T</sub>	Test Current
I <sub>F</sub>	Forward Current
V <sub>F</sub>	Forward Voltage @ I <sub>F</sub>
P <sub>pk</sub>	Peak Power Dissipation
С	Capacitance @ V <sub>R</sub> = 0 and f = 1.0 MHz





#### **ELECTRICAL CHARACTERISTICS**

	$V_{BR}$				Capacitance	Max V <sub>F</sub> @ I <sub>F</sub> = 200	v <sub>c</sub>
Device*	Min	Nom	Max	Leakage Current I <sub>RM</sub> @ V <sub>RWM</sub> = 3 V (μA)	@ 0 V Bias (pF)	mA (V)	Per IEC61000-4-2 (Note 4)
MSQA6V1W5T2G	6.1	6.6	7.2	1.0	90	1.25	Figures 1 and 2 See Below

<sup>3.</sup>  $V_{BR}$  is measured with a pulse test current  $I_T$  at an ambient temperature of 25°C.

<sup>4.</sup> For test procedure see Figures 3 and 4 and Application Note AND8307/D.

<sup>\*</sup>Include SZ-prefix devices where applicable.

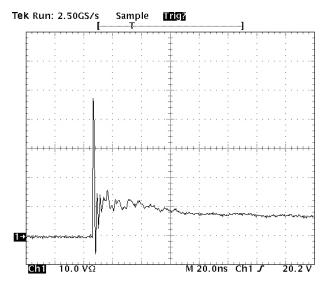


Figure 1. ESD Clamping Voltage Screenshot Positive 8 kV Contact per IEC61000-4-2

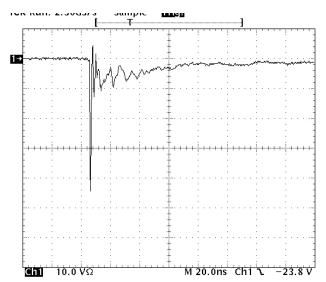


Figure 2. ESD Clamping Voltage Screenshot Negative 8 kV Contact per IEC61000-4-2

#### IEC 61000-4-2 Spec.

Level	Test Volt- age (kV)	First Peak Current (A)	Current at 30 ns (A)	Current at 60 ns (A)
1	2	7.5	4	2
2	4	15	8	4
3	6	22.5	12	6
4	8	30	16	8

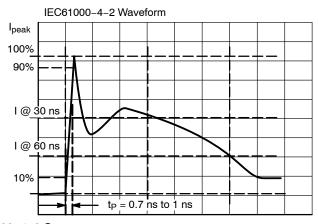


Figure 3. IEC61000-4-2 Spec

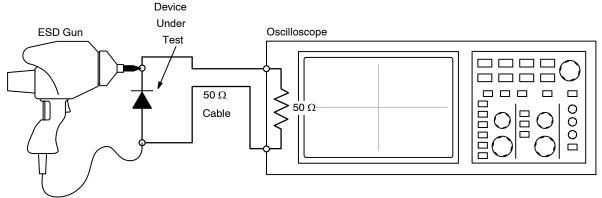


Figure 4. Diagram of ESD Test Setup

The following is taken from Application Note AND8308/D – Interpretation of Datasheet Parameters for ESD Devices.

#### **ESD Voltage Clamping**

For sensitive circuit elements it is important to limit the voltage that an IC will be exposed to during an ESD event to as low a voltage as possible. The ESD clamping voltage is the voltage drop across the ESD protection diode during an ESD event per the IEC61000-4-2 waveform. Since the IEC61000-4-2 was written as a pass/fail spec for larger

systems such as cell phones or laptop computers it is not clearly defined in the spec how to specify a clamping voltage at the device level. ON Semiconductor has developed a way to examine the entire voltage waveform across the ESD protection diode over the time domain of an ESD pulse in the form of an oscilloscope screenshot, which can be found on the datasheets for all ESD protection diodes. For more information on how ON Semiconductor creates these screenshots and how to interpret them please refer to AND8307/D.

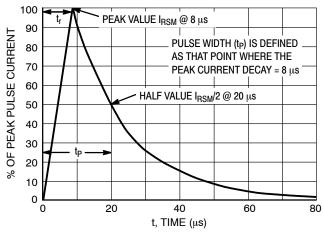


Figure 5. 8 x 20 μs Pulse Waveform

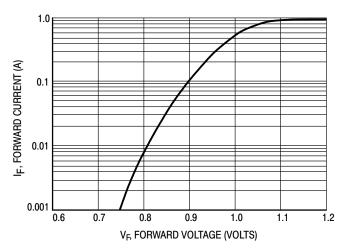


Figure 6. Forward Voltage

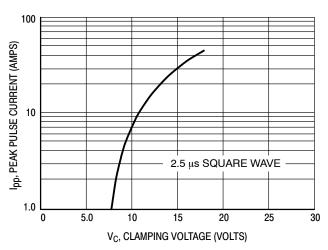


Figure 7. Clamping Voltage versus Peak Pulse Current (Reverse Direction)

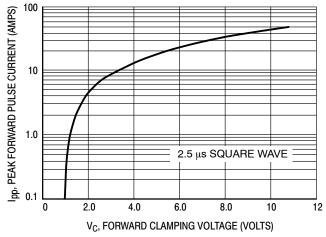


Figure 8. Clamping Voltage versus Peak Pulse Current (Forward Direction)

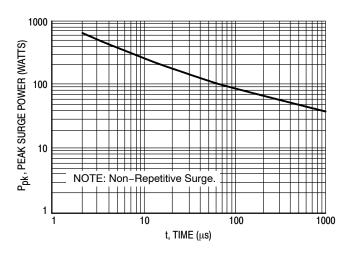


Figure 9. Pulse Width

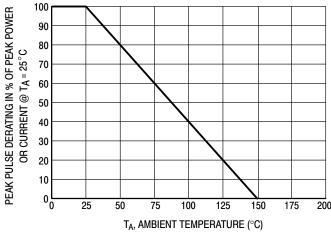


Figure 10. Pulse Derating Curve

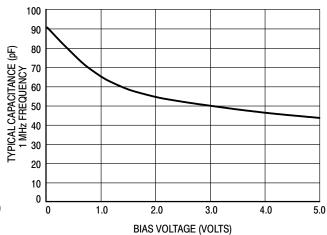


Figure 11. Capacitance



#### SC-88A (SC-70-5/SOT-353) CASE 419A-02 **ISSUE L**

**DATE 17 JAN 2013** 



- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- 419A-01 OBSOLETE. NEW STANDARD 3.
- 419A-02.
  DIMENSIONS A AND B DO NOT INCLUDE
- MOLD FLASH, PROTRUSIONS, OR GATE BURRS

	INC	HES	MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.071	0.087	1.80	2.20
В	0.045	0.053	1.15	1.35
С	0.031	0.043	0.80	1.10
D	0.004	0.012	0.10	0.30
G	0.026	BSC	0.65 BSC	
Н		0.004		0.10
J	0.004	0.010	0.10	0.25
K	0.004	0.012	0.10	0.30
N	0.008	REF	0.20	REF
S	0.079	0.087	2 00	2 20





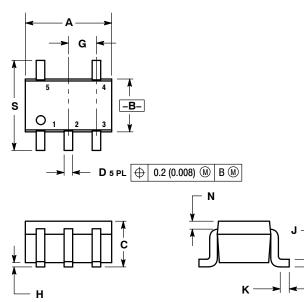
XXX = Specific Device Code

= Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.



SOLDER FOOTPRINT

0.50 0.0197

			0.65 0.025
0.40			0.65 0.025
	<u>1.9</u> 0.0748	SCALE 20:1	$\left(\frac{\text{mm}}{\text{inches}}\right)$
STYLE 1:	STYLE 2:	STYLE 3:	

STYLE 4: STYLE 5: PIN 1. BASE 2. EMITTER PIN 1. SOURCE 1 2. DRAIN 1/2 PIN 1. ANODE 2. EMITTER PIN 1. ANODE 1 2. N/C PIN 1. CATHODE 2. COMMON ANODE 3. ANODE 2 3 BASE 3 BASE 3. SOURCE 1 3. CATHODE 2 4. COLLECTOR 4. CATHODE 2 4. CATHODE 3 4. COLLECTOR 4. GATE 1 5. COLLECTOR 5. CATHODE 5. CATHODE 1 5. GATE 2 5. CATHODE 4

STYLE 9: STYLE 6: STYLE 7: STYLE 8: Note: Please refer to datasheet for PIN 1. CATHODE
2. COLLECTOR
3. N/C
4. BASE PIN 1. ANODE 2. CATHODE 3. ANODE PIN 1. EMITTER 2 2. BASE 2 PIN 1. BASE 2. EMITTER style callout. If style type is not called 3. EMITTER 1 3. BASE out in the datasheet refer to the device 4. COLLECTOR 4. COLLECTOR datasheet pinout or pin assignment. 5 ANODE 5. COLLECTOR 2/BASE 1 5. COLLECTOR 5. EMITTER

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